What is claimed is:

1. A light-emitting diode illuminated light-emitting module, comprising an optical processing board; a transparent substrate located below said optical processing board; and a reflection board located below said transparent substrate, wherein the electrode pads and the associated connections connecting between the electrode pads are placed on said transparent substrate; the light-emitting diode chips, which are placed to emit light toward said reflection board, are installed on said electrode pads; and the reflection mirrors are placed on the surface of said reflection board near said LED chips.

2. The light-emitting diode illuminated light-emitting module according to Claim 1, wherein, said reflection board has a parabolic structure.

3. The light-emitting diode illuminated light-emitting module according to Claim 1, wherein, said reflection board has a plane board structure.

4. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, said optical processing board is a convergence lens.

5. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, said optical processing board is a divergence lens.

6. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, the light reflection cavity board is placed below said reflection board, and the outgoing holes for the electrodes are placed on said light reflection cavity board.

7. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, said electrode pads and the associated connections are made of the transparent and conductive materials.

8. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, said optical processing board and said transparent substrate are produced as an integral.

9. The light-emitting diode illuminated light-emitting module according to Claim 6, wherein, the fix holes or fix pins are placed at the bottom part or the side part, or the bottom part and the side part of said light reflection cavity board.

10. The light-emitting diode illuminated light-emitting module according to Claim 2, wherein, the insulation materials are coated over the surface of said electrode pads and the associated connections of said transparent substrate.

11. The light-emitting diode illuminated light-emitting module according to Claim 2, wherein, the spaces corresponding to the electrode pads and the associated connections of the transparent substrate are reserved on the reflection mirrors of the reflection board.

12. The light-emitting diode illuminated light-emitting module according to Claim 2,

wherein, said light-emitting diode chips are placed at the focus of said parabolic reflection board.

13. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, said light-emitting module is constructed by a single reflection board only, and comprising a single light-emitting diode chip only, to configure a monomeric structure.

14. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, a plurality of the light-emitting diode chips are included in said light-emitting module, and a plurality of the light-emitting diode chips may be arranged in a line to configure an in-line structure.

15. The light-emitting diode illuminated light-emitting module according to Claim 1, 2, or 3, wherein, a plurality of the light-emitting diode chips are included in said light-emitting module, and a plurality of the light-emitting diode chips may be arranged in a plurality of lines to configure an array structure.

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